

B230NH03L-VB Datasheet N-Channel 30 V (D-S) 175 °C MOSFET

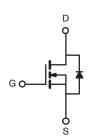
PRODUCT SUMMARY				
V _{DS} (V)	30			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0014			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.0016			
I _D (A)	260			
Configuration	Single			



- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- Package with Low Thermal Resistance
- \bullet 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V_{DS}	30	V	
Gate-Source Voltage	V_{GS}	± 20	V		
Continuous Drain Current	T _C = 25 °C	I _D	260		
Continuous Drain Current	T _C = 125 °C		120 ^a		
Continuous Source Current (Diode Conduction	Is	120	Α		
Pulsed Drain Current ^b	I _{DM}	680			
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	82		
Single Pulse Avalanche Energy	L = 0.1 IIII	E _{AS}	336	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	P _D	375	W	
	T _C = 125 °C		125	VV	
Operating Junction and Storage Temperature I	Range	T _J , T _{stg}	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-Ambient	PCB Mount ^c	R_{thJA}	40	°C/W		
Junction-to-Case (Drain)		R_{thJC}	0.4	C/VV		

Notes

- a. Package limited.
- b. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.

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1



PARAMETER	SYMBOL	vise noted) TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static							1	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		30	-	-	.,	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	1.5	2.0	2.5	V	
Gate-Source Leakage	I _{GSS}	V _{DS} =	0 V, V _{GS} = ± 20 V	-	-	± 100	nA	
		V _{GS} = 0 V	V _{DS} = 30 V	-	-	1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V	V _{DS} = 30 V, T _J = 125 °C	-	-	50	μΑ	
		V _{GS} = 0 V	V _{DS} = 30 V, T _J = 175 °C	-	-	250		
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	V _{DS} ≥ 5 V	120	-	-	Α	
		V _{GS} = 10 V	I _D = 30 A	-	0.0014	-	Ω	
Dunin Course On Otata Basistanas		V _{GS} = 10 V	I _D = 30 A, T _J = 125 °C	-	0.0023	-		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V	I _D = 30 A, T _J = 175 °C	-	0.0028	-		
		V _{GS} = 4.5 V	I _D = 20 A	-	0.0016	-		
Forward Transconductance ^b	9fs	V _{DS} = 15 V, I _D = 30 A		-	190	-	S	
Dynamic ^b								
Input Capacitance	C _{iss}			-	12 484	15 605		
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	V _{DS} = 15 V, f = 1 MHz	-	2204	2755	pF	
Reverse Transfer Capacitance	C _{rss}			-	860	1075		
Total Gate Charge ^c	Qg				179	270		
Gate-Source Charge ^c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 10 \text{ V}, I_{D} = 120 \text{ A}$	-	34	-	nC	
Gate-Drain Charge ^c	Q _{gd}			-	21	-		
Gate Resistance	R _g	f = 1 MHz		0.59	1.19	1.79	Ω	
Turn-On Delay Time ^c	t _{d(on)}				18	27		
Rise Time ^c	t _r	$V_{DD} = 15 \text{ V}, R_L = 0.3 \Omega$ $I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		-	11	17	ns ns	
Turn-Off Delay Time ^c	t _{d(off)}			-	64	96		
Fall Time ^c	t _f			-	11	17		
Source-Drain Diode Ratings and Char	acteristics ^b							
Pulsed Current ^a	I _{SM}			-	-	480	Α	
Forward Voltage	V _{SD}	I _F =	-	0.81	1.5	V		

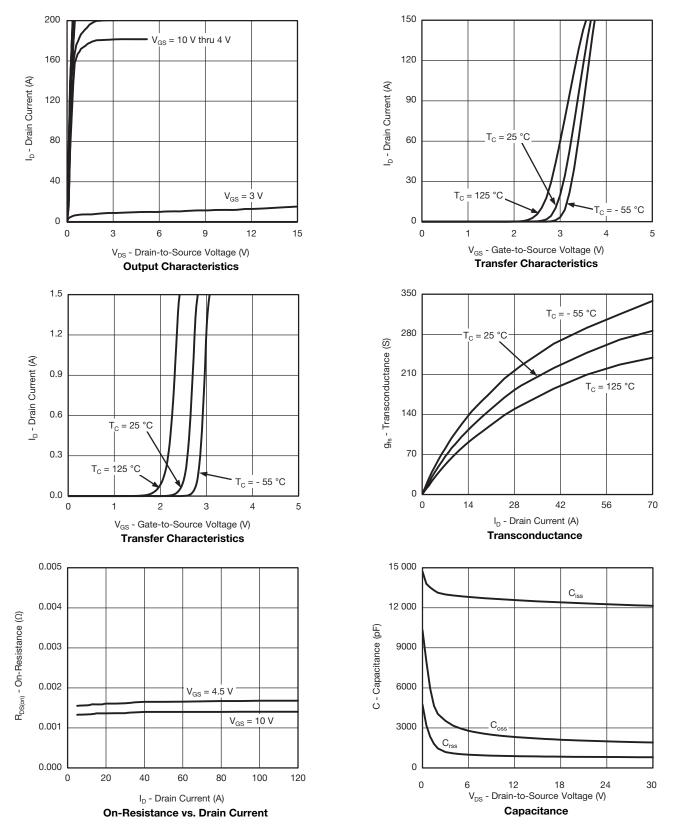
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

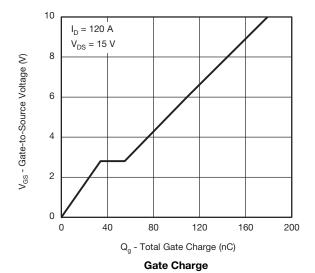


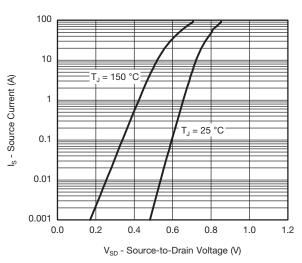
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

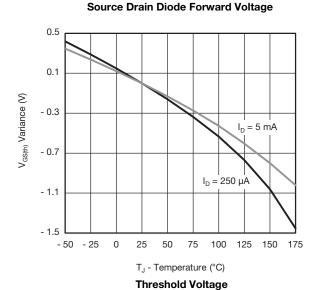


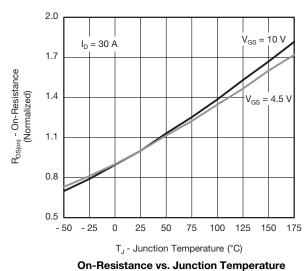


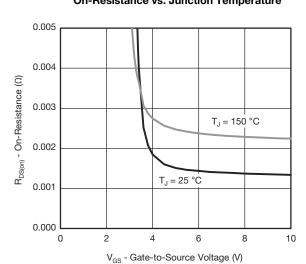
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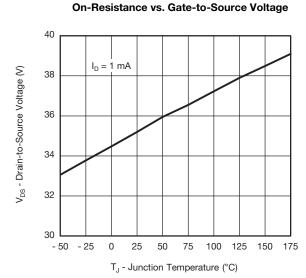








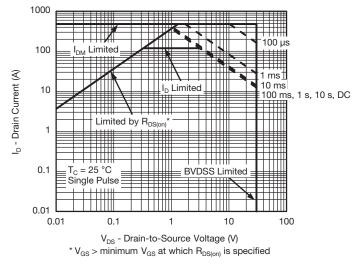




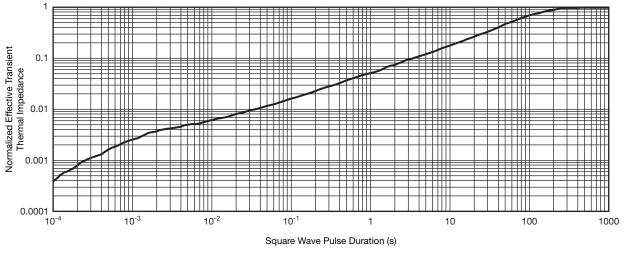
Drain Source Breakdown vs. Junction Temperature



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



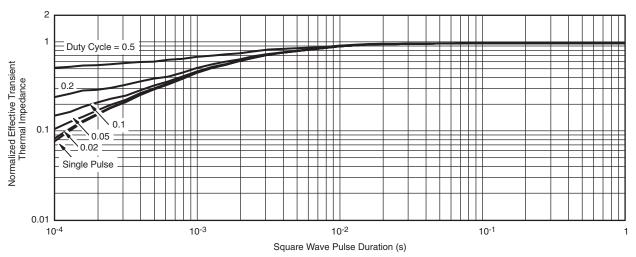
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

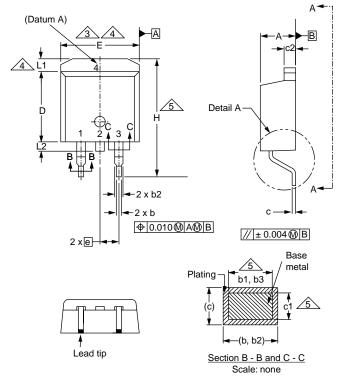
Note

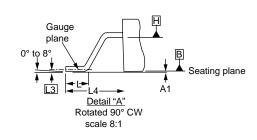
- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

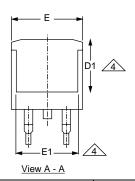
- Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



TO-263AB (HIGH VOLTAGE)







	MILLIN	METERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.06	4.83	0.160	0.190	
A1	0.00	0.25	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	
c2	1.14	1.65	0.045	0.065	
D	0.20	0.65	0.330	0.380	

	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
D1	6.86	-	0.270	-
E	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	1
е	2.54	BSC	0.100 BSC	
Н	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.65	-	0.066
L2	-	1.78	-	0.070
L3	0.25	BSC	0.010	BSC
L4	4.78	5.28	0.188	0.208
		-	-	

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DWG: 5970

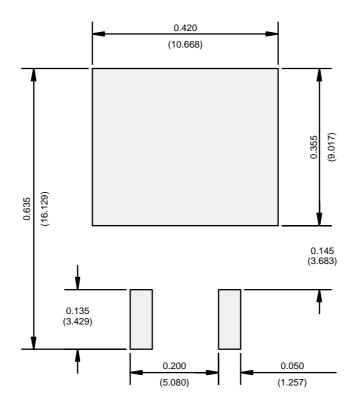
- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Dimensions are shown in millimeters (inches).

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- 3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
- 4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
- 5. Dimension b1 and c1 apply to base metal only.
- 6. Datum A and B to be determined at datum plane H.
- 7. Outline conforms to JEDEC outline to TO-263AB.



RECOMMENDED MINIMUM PADS FOR D PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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